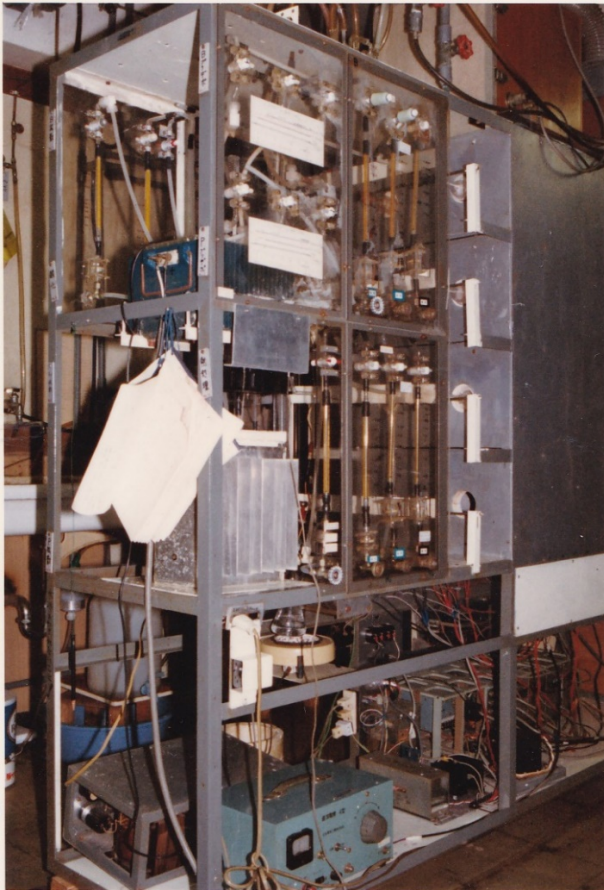
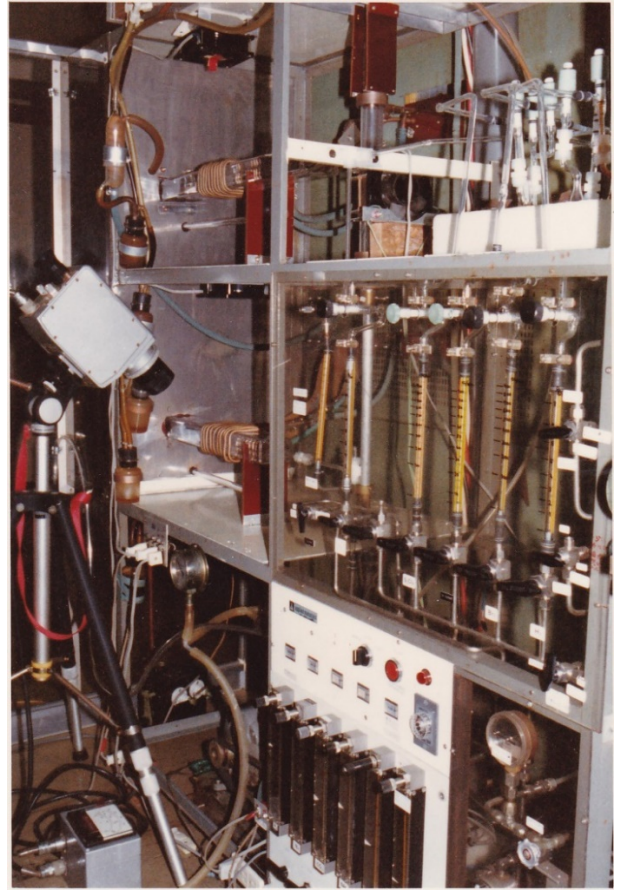


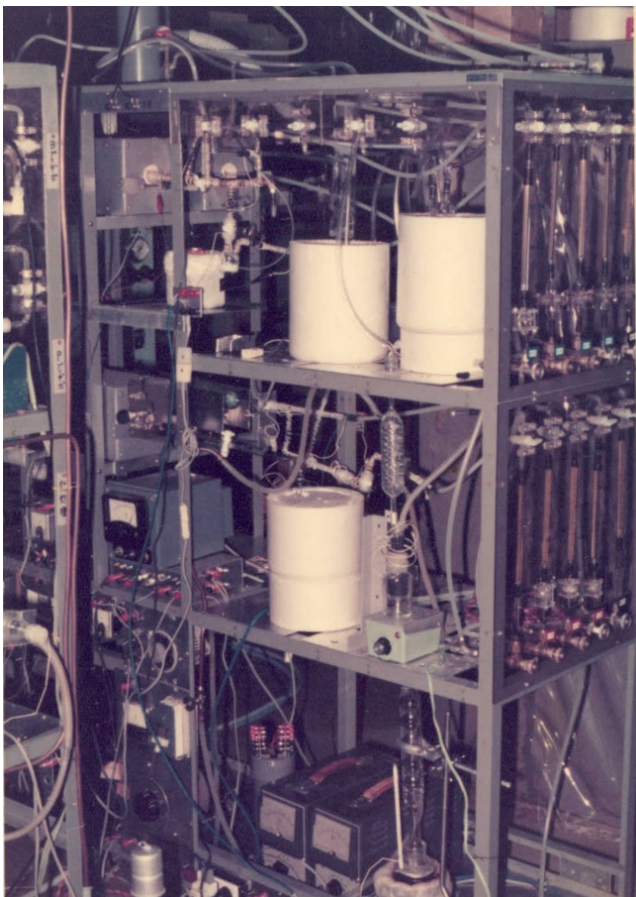
5 Wafer process (2) oxidation, diffusion, CVD



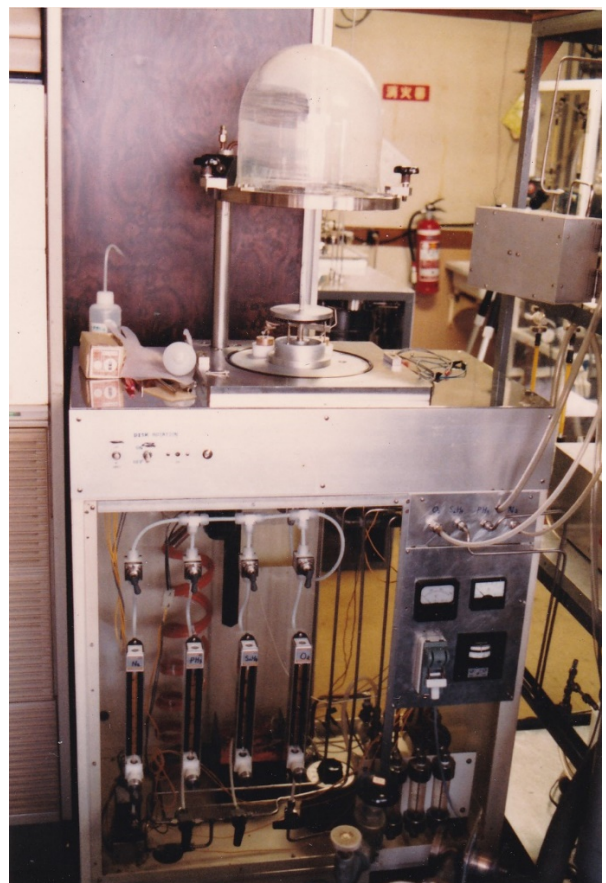
Oxidation diffusion furnace



Atmospheric CVD for Si_3N_4 , SiO_2 , Poly-Si (displayed)



TEOS (tetraethoxysilane) source Al_2O_3 - SiO_2 CVD



Low temperature CVD for SiO_2 (displayed)